



# STGP10NB60SD

N-CHANNEL 10A - 600V - TO-220  
Low Drop PowerMESH™ IGBT

## General features

Type	V <sub>CES</sub>	V <sub>CE(sat)</sub> (Max)@ 25°C	I <sub>C</sub> @ 100°C
STGP10NB60SD	600V	< 1.7V	10A

- HIGH CURRENT CAPABILITY
- HIGH INPUT IMPEDANCE (VOLTAGE DRIVEN)

## Description

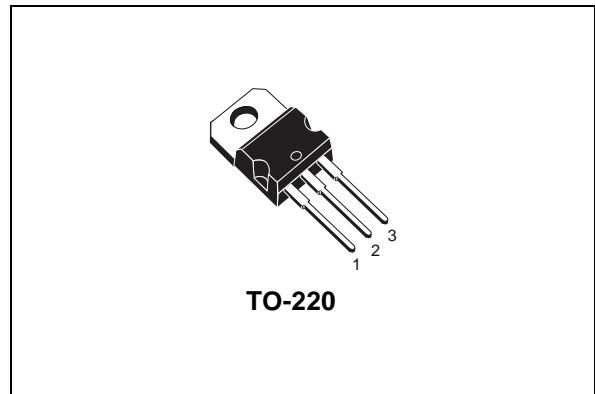
Using the latest high voltage technology based on a patented strip layout, STMicroelectronics has designed an advanced family of IGBTs, the PowerMESH™ IGBTs, with outstanding performances. The suffix "S" identifies a family optimized achieve minimum on-voltage drop for low frequency application (<1kHz).

## Applications

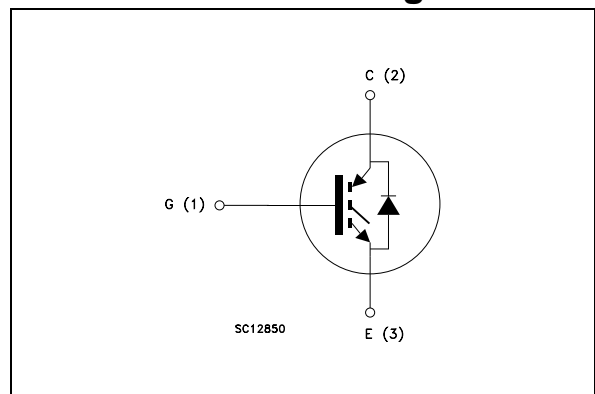
- LIGHT DIMMER
- STATIC RELAYS
- MOTOR CONTROL

## Order codes

Sales Type	Marking	Package	Packaging
STGP10NB60SD	GP10NB60SD	TO-220	TUBE



## Internal schematic diagram



# 1 Electrical ratings

**Table 1. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{CES}$	Collector-Emitter Voltage ( $V_{GS} = 0$ )	600	V
$I_C$ <i>Note 5</i>	Collector Current (continuous) at $T_C = 25^\circ\text{C}$	20	A
$I_C$ <i>Note 5</i>	Collector Current (continuous) at $T_C = 100^\circ\text{C}$	10	A
$I_{CM}$ <i>Note 1</i>	Collector Current (pulsed)	80	W
$V_{GE}$	Gate-Emitter Voltage	$\pm 20$	A
$P_{TOT}$	Total Dissipation at $T_C = 25^\circ\text{C}$	31.5	W
$T_{stg}$	Storage Temperature	– 65 to 150	$^\circ\text{C}$
$T_j$	Operating Junction Temperature		

**Table 2. Thermal resistance**

Rthj-case	Thermal Resistance Junction-case Max	4.7	$^\circ\text{C}/\text{W}$
Rthj-amb	Thermal Resistance Junction-ambient Max	62.5	$^\circ\text{C}/\text{W}$
Rthc-sink	Thermal resistance Case-sink Typ	0.5	

## 2 Electrical characteristics

( $T_{CASE} = 25\text{ °C}$  unless otherwise specified)

**Table 3. Static**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{BR(CES)}$	Collector-Emitter Breakdown Voltage	$I_C = 250\mu A, V_{GE} = 0$	600			V
$V_{BR(CES)}$	Collector-Emitter Breakdown Voltage	$I_C = 1mA, V_{GE} = 0$	20			V
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$V_{GE} = 15V, I_C = 5A$		1.15		V
		$V_{GE} = 15V, I_C = 10A$		1.35	1.7	V
		$V_{GE} = 15V, I_C = 10A, T_C = 125\text{ °C}$		1.25		V
$V_{GE(th)}$	Gate Threshold Voltage	$V_{CE} = V_{GE}, I_C = 250\mu A$	2.5		5	V
$I_{CES}$	Collector cut-off Current ( $V_{GE} = 0$ )	$V_{CE} = \text{Max Rating}, T_C = 25\text{ °C}$			10	$\mu A$
		$V_{CE} = \text{Max Rating}, T_C = 125\text{ °C}$			100	$\mu A$
$I_{GES}$	Gate-Emitter Leakage Current ( $V_{CE} = 0$ )	$V_{GE} = \pm 20V, V_{CE} = 0$			$\pm 100$	nA
$g_{fs}$	Forward Transconductance	$V_{CE} = 25V, I_C = 10A$	5			S

**Table 4. Dynamic**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$C_{ies}$	Input Capacitance	$V_{CE} = 25V, f = 1MHz, V_{GE} = 0$		610		pF
$C_{oes}$	Output Capacitance			65		pF
$C_{res}$	Reverse Transfer Capacitance				12	pF
$Q_g$	Total Gate Charge	$V_{CE} = 400V, I_C = 5A, V_{GE} = 15V, (\text{see Figure 17})$		33		nC
$I_{CL}$	Latching Current	$V_{clamp} = 480V, R_G = 1k\Omega, T_j = 125\text{ °C}$	20			A

**Table 5. Switching On/Off (inductive load)**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on Delay Time	$V_{CC} = 480V, I_C = 10A$		0.7		ns
$t_r$	Current Rise Time	$R_G = 1k\Omega, V_{GE} = 15V, T_j = 25^\circ C$		0.46		ns
$(di/dt)_{on}$	Turn-on Current Slope	(see Figure 18)		8		A/ $\mu s$
$t_c$	Cross-over Time	$V_{CC} = 480V, I_C = 10A$		2.2		$\mu s$
$t_r(V_{off})$	Off Voltage Rise Time	$R_G = 1k\Omega, V_{GE} = 15V, T_j = 25^\circ C$		1.2		$\mu s$
$t_f$	Current Fall Time	(see Figure 18)		1.2		$\mu s$
$t_c$	Cross-over Time	$V_{CC} = 480V, I_C = 10A$		3.8		$\mu s$
$t_r(V_{off})$	Off Voltage Rise Time	$R_G = 1k\Omega, V_{GE} = 15V, T_j = 125^\circ C$		1.2		$\mu s$
$t_f$	Current Fall Time	(see Figure 18)		1.9		$\mu s$

**Table 6. Switching energy (inductive load)**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$E_{on}$ <i>Note 3</i>	Turn-on Switching Losses	$V_{CC} = 480V, I_C = 10A$		0.6		mJ
$E_{off}$ <i>Note 4</i>	Turn-off Switching Losses	$R_G = 1k\Omega, V_{GE} = 15V, T_j = 25^\circ C$		5.0		mJ
$E_{ts}$	Total Switching Losses	(see Figure 18)		5.6		mJ

**Table 7. Collector-emitter diode**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$I_F$	Forward Current				7	A
$I_{FM}$	Forward Current pulsed				56	A
$V_f$	Forward On-Voltage	$I_f = 3.5A$ $I_f = 3.5A, T_j = 125^\circ C$		1.4 1.15	1.9	V V
$t_{rr}$	Reverse Recovery Time	$I_f = 7A, V_R = 35V,$		50		ns
$Q_{rr}$	Reverse Recovery Charge	$T_j = 125^\circ C, di/dt = 100A/\mu s$		70		nC
$I_{rrm}$	Reverse Recovery Current	(see Figure 19)		2.7		A

(1) Pulse width limited by max. junction temperature

(2) Pulsed: Pulse duration = 300  $\mu s$ , duty cycle 1.5%

(3)  $E_{on}$  is the turn-on losses when a typical diode is used in the test circuit in figure 2. If the IGBT is offered in a package with a co-pak diode, the co-pak diode is used as external diode. IGBTs & Diode are at the same temperature (25°C and 125°C)

(4) Turn-off losses include also the tail of the collector current

(5) Calculated according to the iterative formula:

$$I_C(T_C) = \frac{T_{JMAX} - T_C}{R_{THJ-C} \times V_{CESAT(MAX)}(T_C, I_C)}$$

## 2.1 Electrical characteristics (curves)

Figure 1. Safe Operating Area

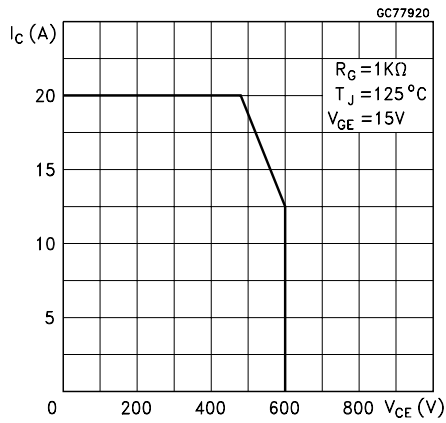


Figure 2. Thermal Impedance

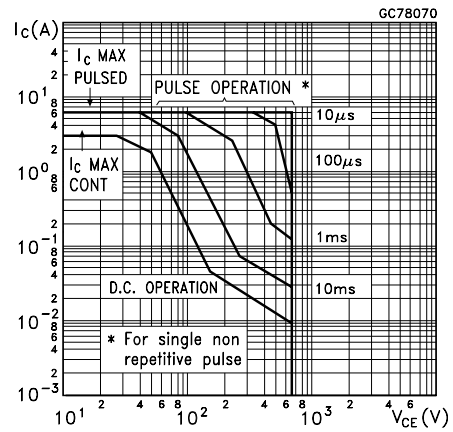


Figure 3. Output Characteristics

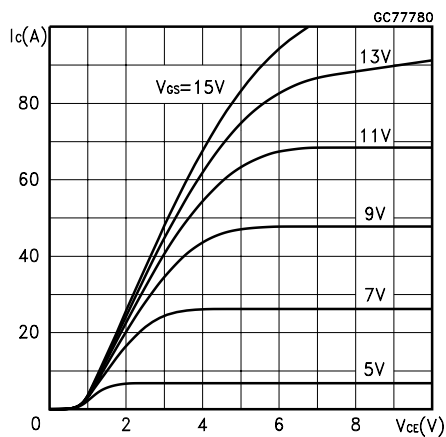


Figure 4. Transfer Characteristics

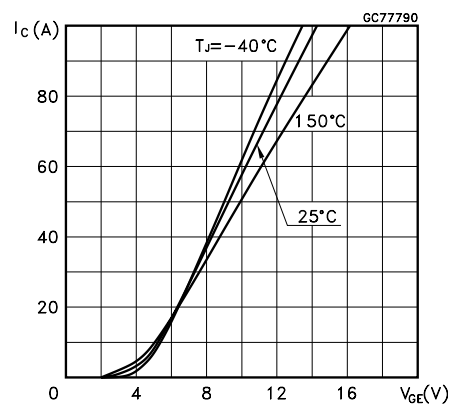


Figure 5. Transconductance

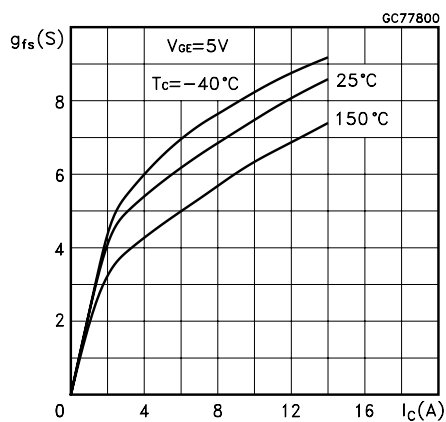
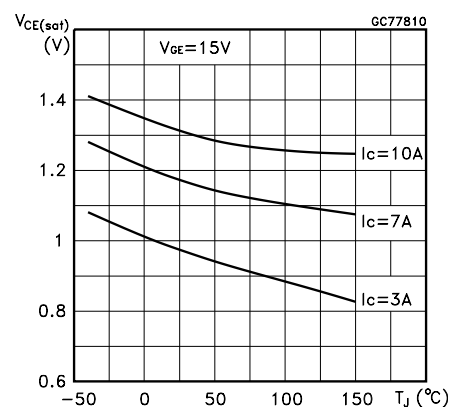
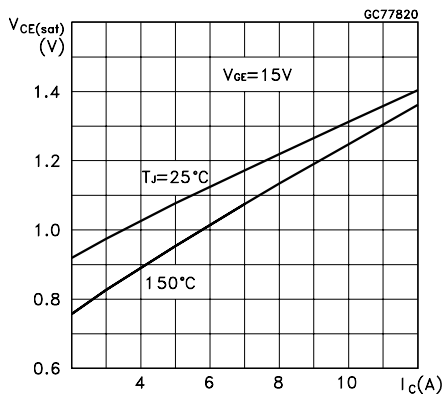


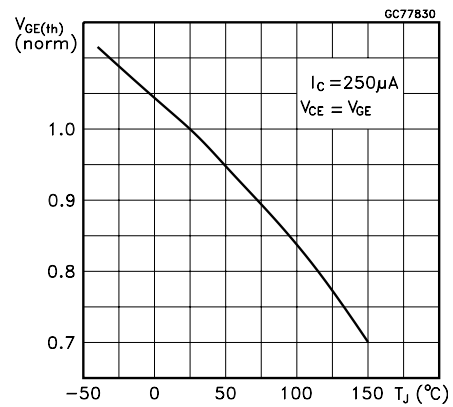
Figure 6. Collector-Emitter on Voltage vs Temperature



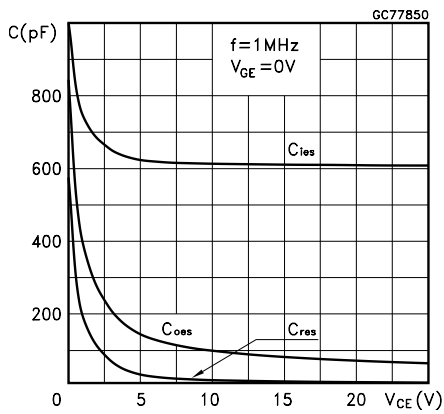
**Figure 7. Collector-Emitter on Voltage vs Collector Current**



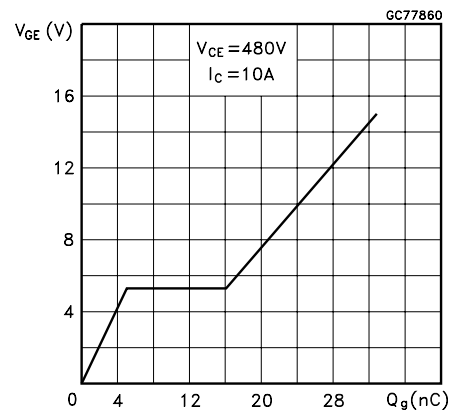
**Figure 8. Gate Threshold Voltage vs Temperature**



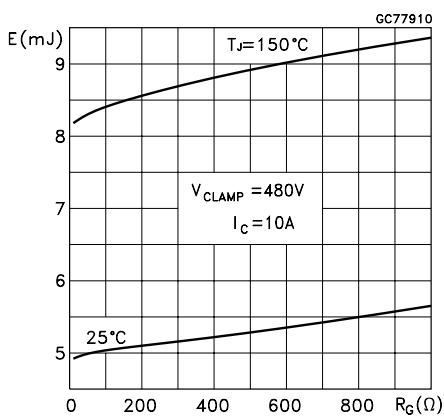
**Figure 9. Capacitance Variations**



**Figure 10. Gate Charge vs Gate-Emitter Voltage**



**Figure 11. Switching Losses vs Gate Resistance**



**Figure 12. Switching Losses vs Collector Current**

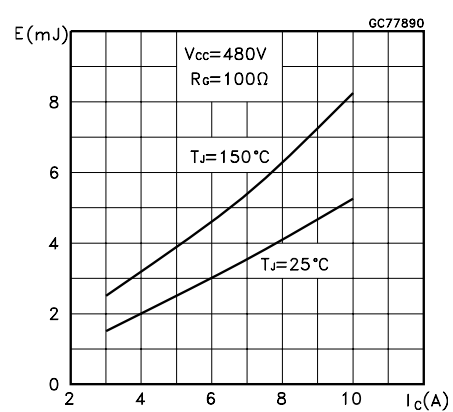


Figure 13. Switching Losses vs Temperature

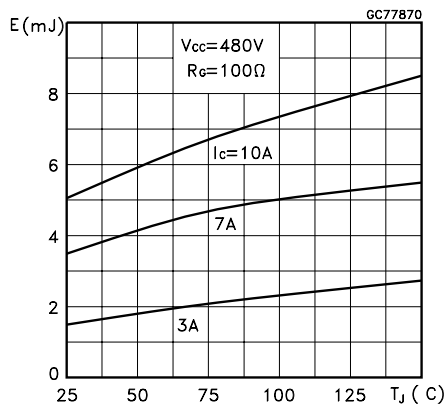


Figure 14. Normalized Breakdown Voltage vs Temperature

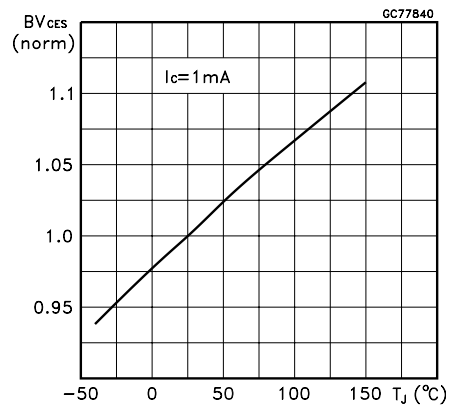
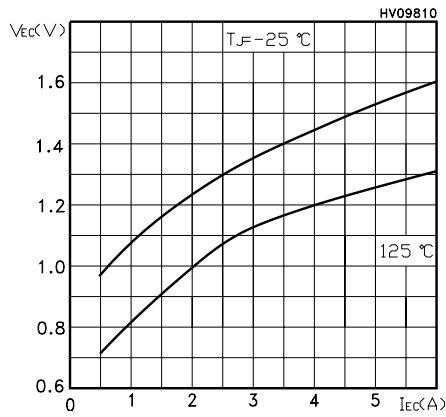


Figure 15. Emitter-Collector Diode Characteristics



### 3 Test Circuits

Figure 16. Test Circuit for Inductive Load Switching

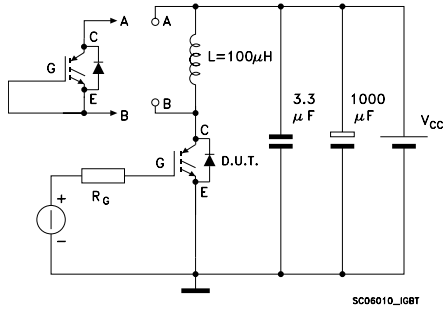


Figure 17. Gate Charge Test Circuit

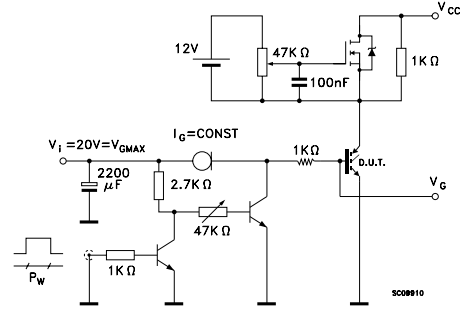


Figure 18. Switching Waveform

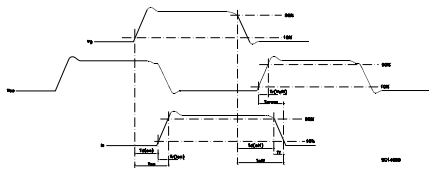
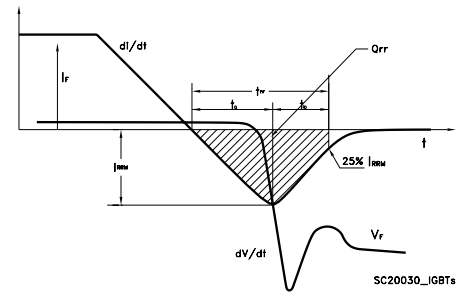


Figure 19. Diode Recovery Time Waveform



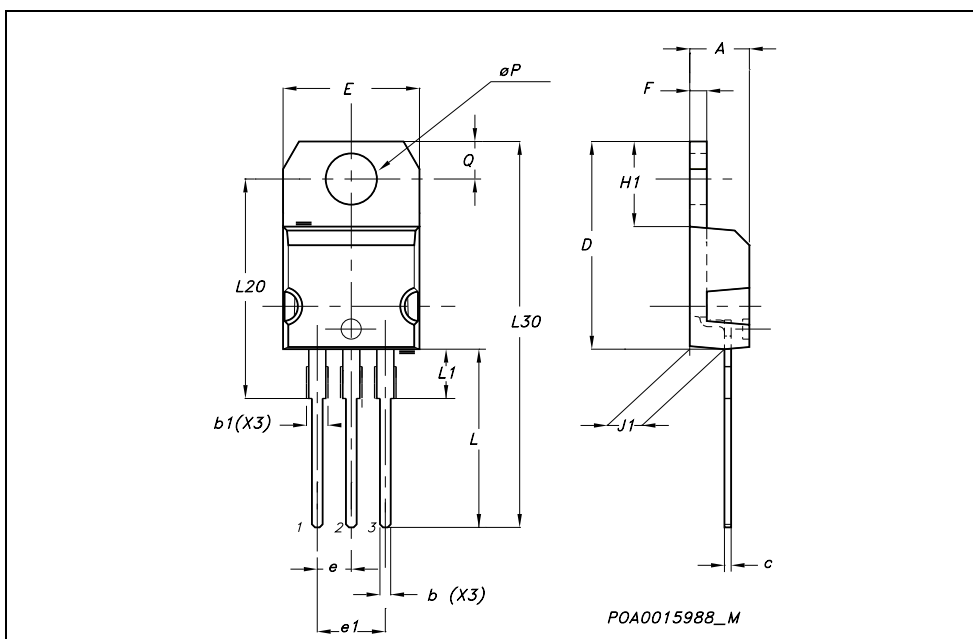


## 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect . The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: [www.st.com](http://www.st.com)

**TO-220 MECHANICAL DATA**

DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A	4.40		4.60	0.173		0.181
b	0.61		0.88	0.024		0.034
b1	1.15		1.70	0.045		0.066
c	0.49		0.70	0.019		0.027
D	15.25		15.75	0.60		0.620
E	10		10.40	0.393		0.409
e	2.40		2.70	0.094		0.106
e1	4.95		5.15	0.194		0.202
F	1.23		1.32	0.048		0.052
H1	6.20		6.60	0.244		0.256
J1	2.40		2.72	0.094		0.107
L	13		14	0.511		0.551
L1	3.50		3.93	0.137		0.154
L20		16.40			0.645	
L30		28.90			1.137	
øP	3.75		3.85	0.147		0.151
Q	2.65		2.95	0.104		0.116



## 5 Revision History

Date	Revision	Changes
18-Nov-2005	1	Initial release.

Information furnished is believed to be accurate and reliable. However, STMicroelectronics assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of STMicroelectronics. Specifications mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information previously supplied. STMicroelectronics products are not authorized for use as critical components in life support devices or systems without express written approval of STMicroelectronics.

The ST logo is a registered trademark of STMicroelectronics.  
All other names are the property of their respective owners

© 2005 STMicroelectronics - All rights reserved

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan -  
Malaysia - Malta - Morocco - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America

[www.st.com](http://www.st.com)